

## TLV4011 Precision Comparator with Integrated Reference

### 1 Features

- Adjustable thresholds down to 1.226 V
- Precision  $\pm 1.5\%$  threshold voltage accuracy
- Supply current: 3  $\mu\text{A}$
- Open-drain output
- Temperature range:  $-40^\circ\text{C}$  to  $85^\circ\text{C}$
- 5-Pin SC-70 package

### 2 Applications

- Electricity meters
- Circuit breakers
- Thermostats
- Cordless power tools

### 3 Description

The TLV4011 is a low-power, high-accuracy comparator with a precision, integrated reference. Two external resistors can be connected to the input to create an adjustable voltage threshold down to 1.226 V.

The factory-trimmed switching threshold and precision hysteresis combine to make the TLV4011 appropriate for voltage and current monitoring in harsh, noisy environments where slow moving input signals must be converted into clean digital outputs. Similarly, brief glitches on the input are rejected thereby ensuring stable output operation without false triggering.

During power on, RESET is asserted (LOW) when the supply voltage  $V_{DD}$  becomes higher than 0.8 V. Thereafter, the TLV4011 monitors the input and keeps RESET active (LOW) while the input remains below the threshold voltage  $V_{IT}$ . As soon as the input rises above the threshold voltage  $V_{IT}$ , RESET is deasserted (HIGH). The product spectrum is designed for 1.8-V, 3.3-V, 5-V, and adjustable supply voltages.

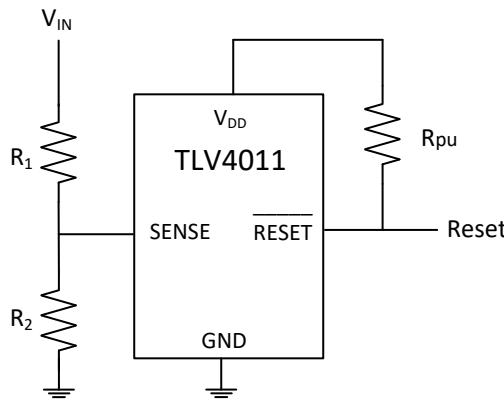
The TLV4011 is available in a 5-pin SC-70 package and are characterized for operation over a temperature range of  $-40^\circ\text{C}$  to  $85^\circ\text{C}$ .

### Device Information<sup>(1)</sup>

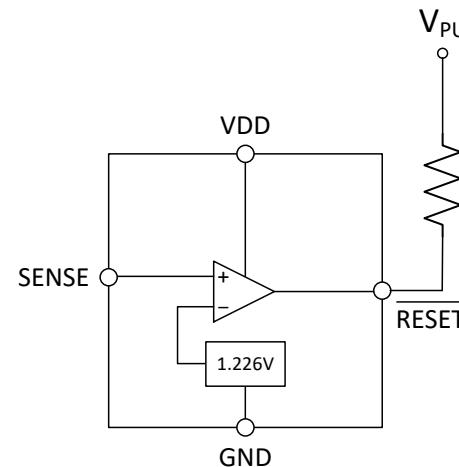
PART NUMBER	PACKAGE	BODY SIZE (NOM)
TLV4011	SC-70 (5)	2.00 mm x 1.25 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

### Typical Application Schematic



### Block Diagram



An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

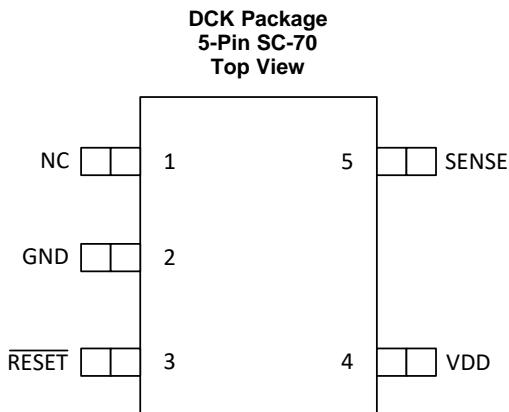
## Table of Contents

<b>1</b>	<b>Features</b>	<b>1</b>	7.2	Functional Block Diagram	8
<b>2</b>	<b>Applications</b>	<b>1</b>	7.3	Feature Description	8
<b>3</b>	<b>Description</b>	<b>1</b>	7.4	Device Functional Modes	9
<b>4</b>	<b>Revision History</b>	<b>2</b>	<b>8</b>	<b>Application and Implementation</b>	<b>10</b>
<b>5</b>	<b>Pin Configuration and Functions</b>	<b>3</b>	8.1	Application Information	10
<b>6</b>	<b>Specifications</b>	<b>4</b>	8.2	Typical Application	10
6.1	Absolute Maximum Ratings	4	<b>9</b>	<b>Power Supply Recommendations</b>	<b>12</b>
6.2	ESD Ratings	4	<b>10</b>	<b>Layout</b>	<b>13</b>
6.3	Recommended Operating Conditions	4	10.1	Layout Guidelines	13
6.4	Thermal Information	4	10.2	Layout Examples	13
6.5	Electrical Characteristics	5	<b>11</b>	<b>Device and Documentation Support</b>	<b>14</b>
6.6	Timing Requirements	5	11.1	Receiving Notification of Documentation Updates	14
6.7	Switching Characteristics	5	11.2	Support Resources	14
6.8	Dissipation Ratings	5	11.3	Trademarks	14
6.9	Typical Characteristics	7	11.4	Electrostatic Discharge Caution	14
<b>7</b>	<b>Detailed Description</b>	<b>8</b>	11.5	Glossary	14
7.1	Overview	8	<b>12</b>	<b>Mechanical, Packaging, and Orderable Information</b>	<b>15</b>

## 4 Revision History

DATE	REVISION	NOTES
March 2020	*	Initial release

## 5 Pin Configuration and Functions



### Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
GND	2	I	Ground
<u>RESET</u>	3	O	Active-low reset output (open-drain)
SENSE	5	I	Input
NC	1	—	No internal connection
V <sub>DD</sub>	4	I	Input supply voltage

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
$V_{DD}$	Supply voltage <sup>(2)</sup>	-0.3	7	V
	Voltage applied to all other pins <sup>(2)</sup>	-0.3	7	V
$I_{OL}$	Maximum low-level output current		5	mA
$I_{OH}$	Maximum high-level output current		-5	mA
$I_{IK}$	Input clamp current $V_I < 0$ or $V_I > V_{DD}$		$\pm 10$	mA
$I_{OK}$	Output clamp current $V_O < 0$ or $V_O > V_{DD}$		$\pm 10$	mA
$P_D$	Continuous total power dissipation	See <a href="#">Dissipation Ratings</a>		
$T_A$	Operating free-air temperature	-40	85	°C
$T_{solder}$	Soldering temperature		260	°C
$T_{stg}$	Storage temperature	-65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values are with respect to GND. For reliable operation, the device should not be continuously operated at 7 V for more than  $t = 1000$  h.

### 6.2 ESD Ratings

		VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	$\pm 2000$
		Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	$\pm 1000$

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP155 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

		MIN	MAX	UNIT
$V_{DD}$	Supply voltage	1.3	6	V
$V_I$	Input voltage	0	$V_{DD} + 0.3$	V
$T_A$	Operating free-air temperature	-40	85	°C

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>	TLV4011	UNIT	
	DCK (SC-70)		
	5 PINS		
$R_{\theta JA}$	Junction-to-ambient thermal resistance	246.6	°C/W
$R_{\theta JC(\text{top})}$	Junction-to-case (top) thermal resistance	68.2	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	78.4	°C/W
$\Psi_{JT}$	Junction-to-top characterization parameter	0.9	°C/W
$\Psi_{JB}$	Junction-to-board characterization parameter	77.7	°C/W
$R_{\theta JC(\text{bot})}$	Junction-to-case (bottom) thermal resistance	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

## 6.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V <sub>OL</sub> Low-level output voltage		V <sub>DD</sub> = 1.5 V, I <sub>OL</sub> = 1 mA	0.3			V
		V <sub>DD</sub> = 3.3 V, I <sub>OL</sub> = 2 mA				
		V <sub>DD</sub> = 6 V, I <sub>OL</sub> = 3 mA				
V <sub>POR</sub> Power-up reset voltage <sup>(1)</sup>	V <sub>OL</sub> (max) = 0.2 V, I <sub>OL</sub> = 50 $\mu$ A, T <sub>A</sub> = 25°C		0.8			V
V <sub>IT</sub> Negative-going input threshold voltage <sup>(2)</sup>	SENSE		1.2	1.226	1.244	V
V <sub>hys</sub> Hysteresis	T <sub>A</sub> = 25°C		15			mV
I <sub>I</sub> Input current	SENSE		-25		25	nA
I <sub>OH</sub> High-level output current at <u>RESET</u>	<u>RESET</u>	SENSE = V <sub>IT</sub> + 0.2 V, V <sub>OH</sub> = V <sub>DD</sub>			300	nA
I <sub>DD</sub> Supply current		V <sub>DD</sub> = 3.3 V, Output unconnected	2	4		$\mu$ A
		V <sub>DD</sub> = 6 V, Output unconnected	2	4		
C <sub>I</sub> Input capacitance	V <sub>I</sub> = 0 V to V <sub>DD</sub>		1			pF

(1) The lowest supply voltage at which RESET (V<sub>OL</sub>(max) = 0.2 V, I<sub>OL</sub> = 50  $\mu$ A) becomes active. t<sub>r</sub>(V<sub>DD</sub>)  $\geq$  15  $\mu$ s/V.

(2) To ensure the best stability of the threshold voltage, place a bypass capacitor (ceramic, 0.1- $\mu$ F) near the supply terminals.

## 6.6 Timing Requirements

R<sub>L</sub> = 1 M $\Omega$ , C<sub>L</sub> = 50 pF, T<sub>A</sub> = -40°C to 85°C (unless otherwise noted)

			MIN	MAX	UNIT
t <sub>w</sub> Pulse duration	SENSE	V <sub>IH</sub> = 1.05 $\times$ V <sub>IT</sub> , V <sub>IL</sub> = 0.95 $\times$ V <sub>IT</sub>	5.5		$\mu$ s

## 6.7 Switching Characteristics

R<sub>L</sub> = 1 M $\Omega$ , C<sub>L</sub> = 50 pF, T<sub>A</sub> = -40°C to 85°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t <sub>PHL</sub> Propagation (delay) time, high-to-low-level output	SENSE to <u>RESET</u> delay	V <sub>IH</sub> = 1.05 $\times$ V <sub>IT</sub> , V <sub>IL</sub> = 0.95 $\times$ V <sub>IT</sub>	5	100		$\mu$ s
t <sub>PLH</sub> Propagation (delay) time, low-to-high-level output	SENSE to <u>RESET</u> delay	V <sub>IH</sub> = 1.05 $\times$ V <sub>IT</sub> , V <sub>IL</sub> = 0.95 $\times$ V <sub>IT</sub>	5	100		$\mu$ s

## 6.8 Dissipation Ratings

PACKAGE	POWER RATING T <sub>A</sub> < 25°C	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	POWER RATING T <sub>A</sub> = 70°C	POWER RATING T <sub>A</sub> = 85°C
DCK	321 mW	2.6 mW/°C	206 mW	167 mW

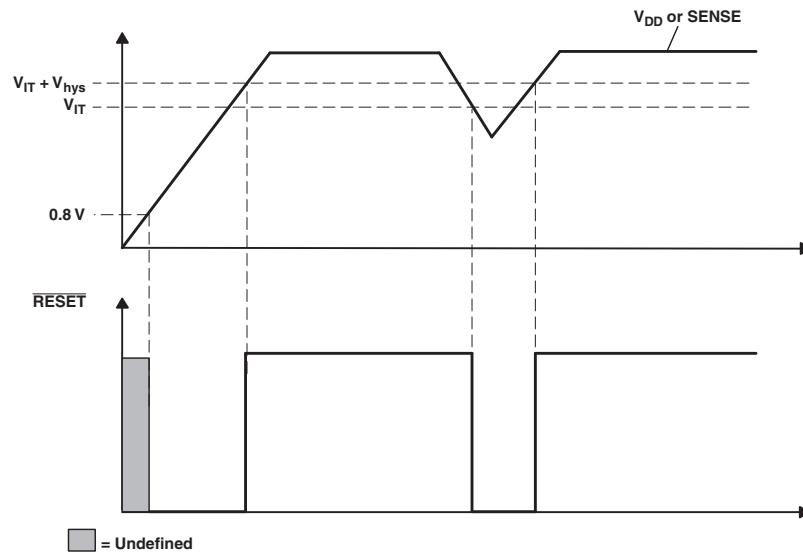
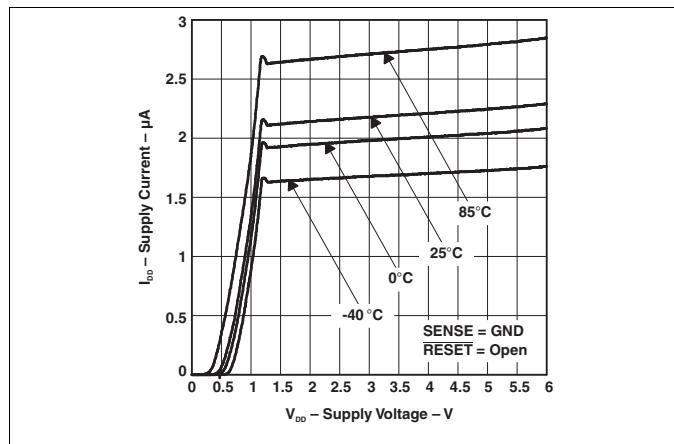
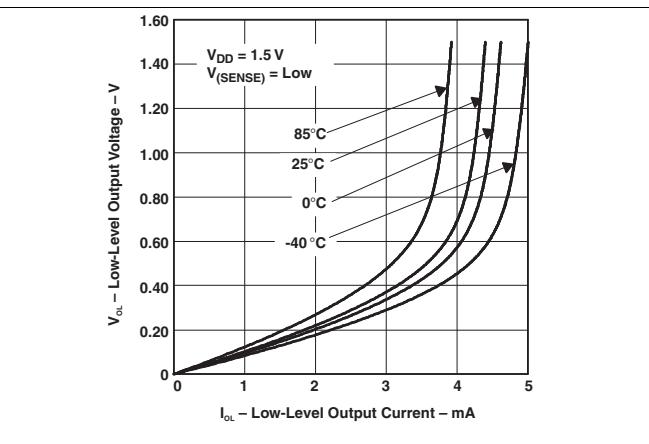


Figure 1. Timing Requirements

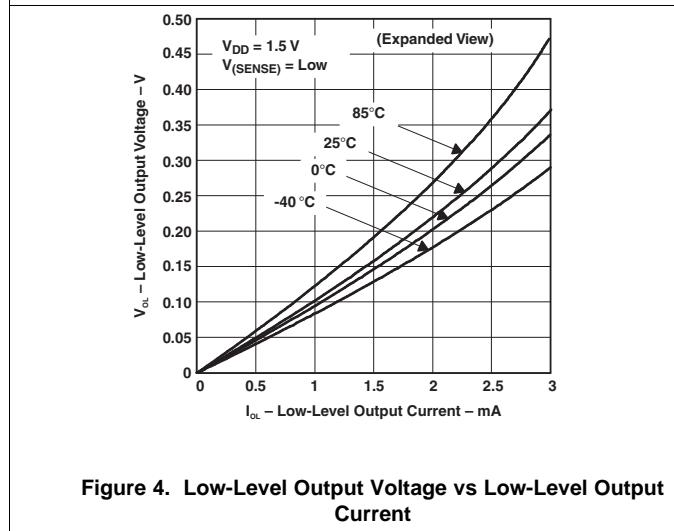
## 6.9 Typical Characteristics



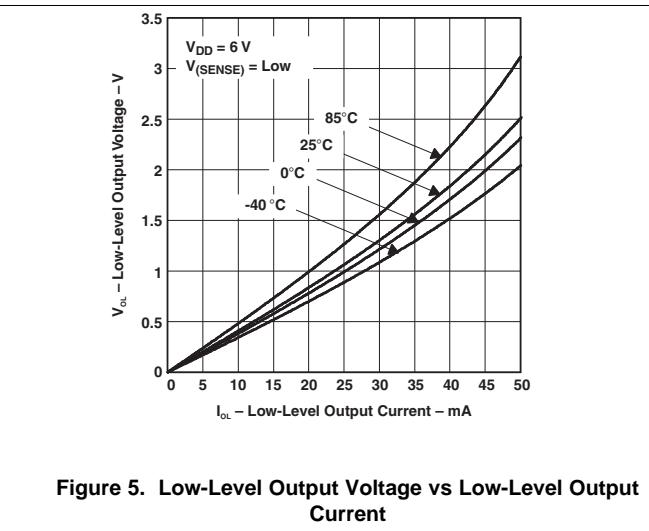
**Figure 2. Supply Current vs Supply Voltage**



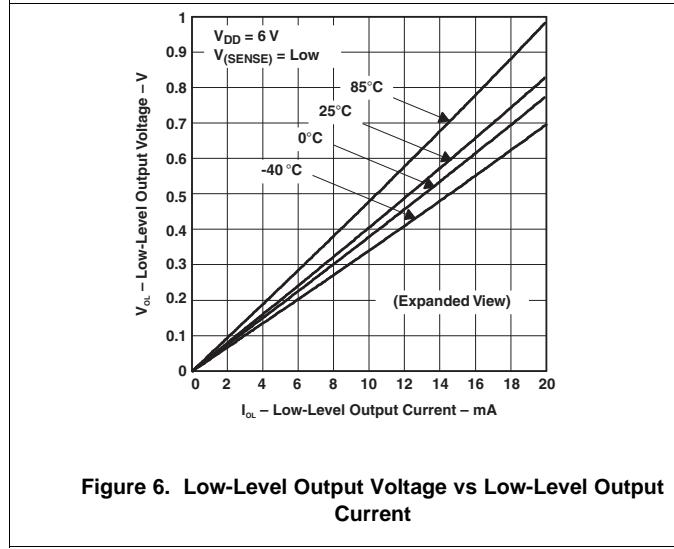
**Figure 3. Low-Level Output Voltage vs Low-Level Output Current**



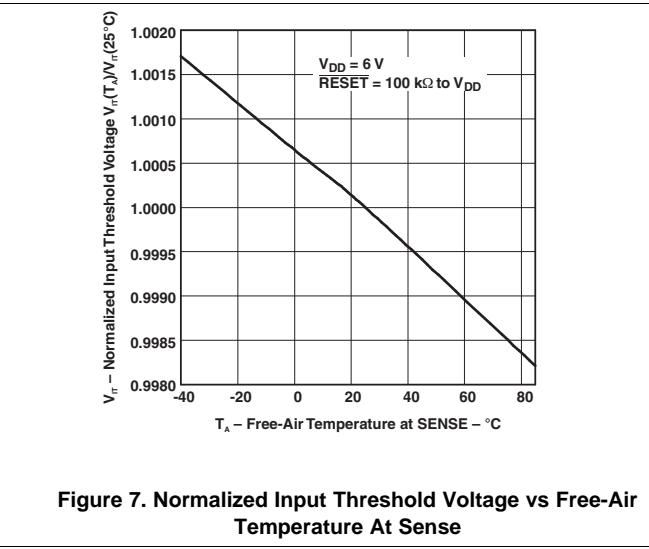
**Figure 4. Low-Level Output Voltage vs Low-Level Output Current**



**Figure 5. Low-Level Output Voltage vs Low-Level Output Current**



**Figure 6. Low-Level Output Voltage vs Low-Level Output Current**



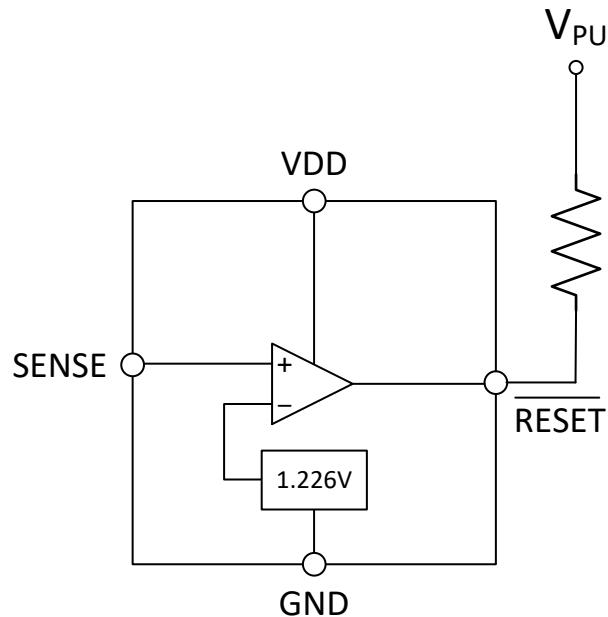
**Figure 7. Normalized Input Threshold Voltage vs Free-Air Temperature At Sense**

## 7 Detailed Description

### 7.1 Overview

The TLV4011 is a low-current comparator used to monitor system voltages above 1.226 V. The comparators assert an active low  $\overline{\text{RESET}}$  signal when the SENSE voltages drop below V<sub>IT</sub>. The  $\overline{\text{RESET}}$  output remains low until the SENSE voltage returns above V<sub>IT</sub> plus the integrated hysteresis level. The TLV4011 is also designed to be immune to short negative transients on the SENSE pin.

### 7.2 Functional Block Diagram



### 7.3 Feature Description

#### 7.3.1 SENSE Monitoring

The SENSE input is where a system voltage can be monitored. If the voltage on this pin drops below V<sub>IT</sub>,  $\overline{\text{RESET}}$  is asserted low. The comparator has a built-in hysteresis to ensure smooth  $\overline{\text{RESET}}$  assertions and de-assertions. By connecting a resistor divider network to the SENSE input as shown in the circuit below, V<sub>IN</sub> is divided down so  $\overline{\text{RESET}}$  will assert when the divided down value of V<sub>IN</sub> reaches V<sub>IT</sub> (1.226 V). The TLV4011 is capable of monitoring any input voltage down to 1.226 V.

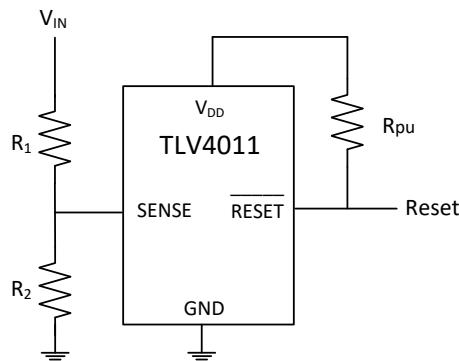


Figure 8. Voltage Monitor

## Feature Description (continued)

### 7.3.2 Transient Immunity

The TLV4011 is immune to short negative transients on the SENSE pin. Sensitivity to transients is dependent on threshold overdrive as shown in [Figure 9](#) and [Figure 10](#). These graphs show the duration that the transient is below  $V_{IT}$  compared to the magnitude of the voltage drop below  $V_{IT}$ , called the threshold overdrive voltage. Any combination of transient duration and overdrive voltage which lies above the curves will result in  $\overline{RESET}$  being asserted low. Any transient which lies below the curves will be ignored by the device.

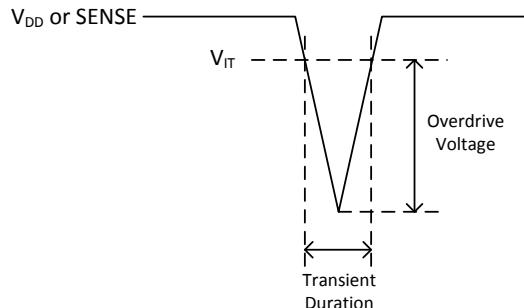


Figure 9. SENSE Overdrive Voltage

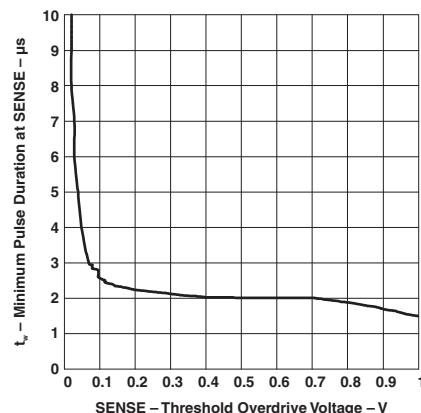


Figure 10. Minimum Pulse Duration at Sense vs Sense Threshold Overdrive Voltage

### 7.4 Device Functional Modes

The SENSE input is used to monitor one supply. When that supply is above the  $V_{IT}$  threshold,  $\overline{RESET}$  will be high. Otherwise,  $\overline{RESET}$  will be low.

Table 1. Function and Truth Table

TLV4011	
SENSE > $V_{IT}$	$\overline{RESET}$
0 (False)	L
1 (True)	H

## 8 Application and Implementation

### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 8.1 Application Information

The TLV4011 comparator is designed to assert an active-low  $\overline{\text{RESET}}$  signal when the SENSE input drops below the voltage threshold  $V_{\text{IT}}$ . The  $\overline{\text{RESET}}$  signal remains low until the voltages return above their respective threshold plus the hysteresis. If additional hysteresis is required, positive feedback can be implemented similar to how it is done on a discrete comparator. See [Application Note](#) for details on how to implement external hysteresis in a non-inverting configuration.

### 8.2 Typical Application

#### 8.2.1 Under-Voltage Detection

Under-voltage detection is frequently required in battery-powered, portable electronics to alert the system that a battery voltage has dropped below the usable voltage level. [Figure 11](#) shows a simple under-voltage detection circuit using the TLV4011 which is a non-inverting comparator with an integrated 1.226 V reference and an open-drain output stage. A non-inverting is well suited for this application since the micro-controller requires an active low signal when an undervoltage level occurs.

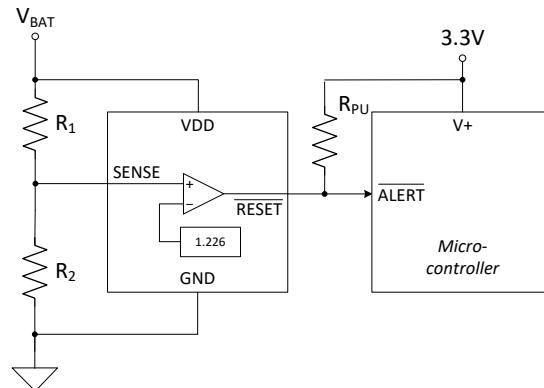


Figure 11. Under-Voltage Detection

##### 8.2.1.1 Design Requirements

For this design, follow these design requirements:

- TLV4011 operates from the  $V_{\text{BAT}}$  directly
- Output is level-shifted to the 3.3 V power supply that powers the microcontroller.
- Under-voltage alert is active low.
- Logic low output when  $V_{\text{BAT}}$  decreases below 2.0V.

##### 8.2.1.2 Detailed Design Procedure

Configure the circuit as shown in [Figure 11](#). Note that VDD of the comparator is connected directly to  $V_{\text{BAT}}$  (the battery being monitored) and the output of the comparator is level shifted with its open-drain output to 3.3 V which powers the micro-controller. Resistors  $R_1$  and  $R_2$  divide down  $V_{\text{BAT}}$  so that the resistor divided output equals 1.226 V when  $V_{\text{BAT}}$  reaches an under-voltage alert level of 2.0 V.

## Typical Application (continued)

When the battery voltage sags down to 2.0 V, the resistor divider voltage crosses the ( $V_{IT} = 1.226$  V) threshold of the TLV4011. This causes the comparator output to transition from a logic high to a logic low. An open-drain comparator is selected so the comparator output is compatible with the input logic level of the microcontroller. In addition, selecting a comparator with an integrated reference value of 1.226 V is favorable because it is the closest internal reference option that is less than the critical under-voltage level of 2.0 V. Choosing the internal reference option that is closest to the critical under-voltage level minimizes the resistor divider ratio which optimizes the accuracy of the circuit. Error at the falling edge threshold of ( $V_{IT}$ ) is amplified by the inverse of the resistor divider ratio. So minimizing the resistor divider ratio is a way of optimizing voltage monitoring accuracy.

Equation 1 is derived from the analysis of Figure 11.

$$V_{IT} = \frac{R_2}{R_1 + R_2} \times V_{BAT} \quad (1)$$

where

- $R_1$  and  $R_2$  are the resistor values for the resistor divider connected to SENSE
- $V_{BAT}$  is the voltage source that is being monitored for an undervoltage condition.
- $V_{IT}$  is the falling edge threshold where the comparator output changes state from high to low

Rearranging Equation 1 and solving for  $R_1$  yields Equation 2.

$$R_1 = \frac{(V_{BAT} - V_{IT})}{V_{IT}} \times R_2 \quad (2)$$

For the specific undervoltage detection of 2.0 V using the TLV4011, the following results are calculated.

$$R_1 = \frac{(2.0 - 1.226)}{1.226} \times 1M = 631 \text{ k}\Omega \quad (3)$$

where

- $R_2$  is set to 1 M $\Omega$
- $V_{BAT}$  is set to 2.0 V
- $V_{IT}$  is set to 1.226 V

Choose  $R_{TOTAL}$  ( $R_1 + R_2$ ) such that the current through the divider is at approximately 100 times higher than the input bias current ( $I_{BIAS}$ ). The resistors can have high values to minimize current consumption in the circuit without adding significant error to the resistive divider.

### 8.2.1.3 Application Curve

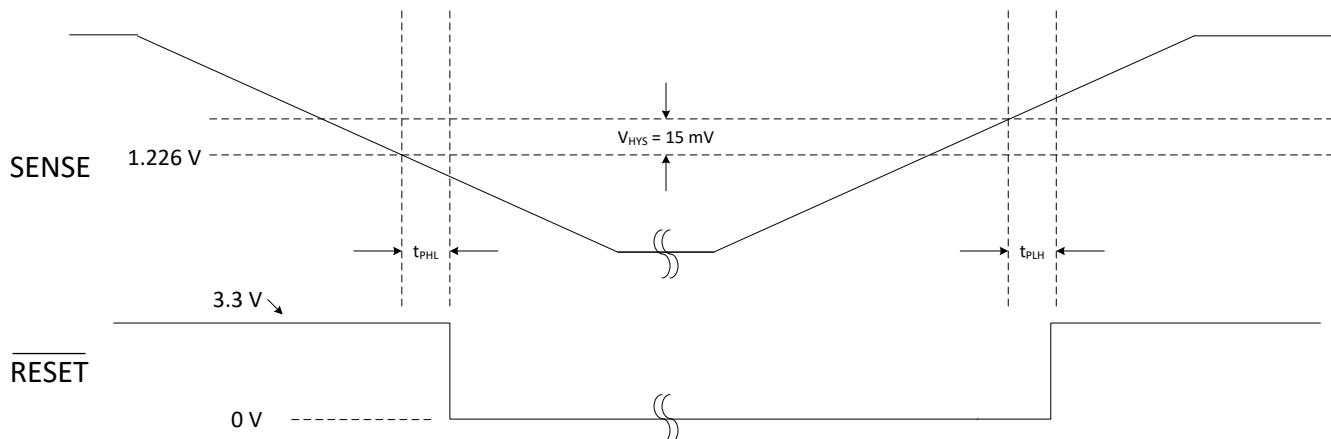


Figure 12. Under-Voltage Detection

## Typical Application (continued)

### 8.2.2 Additional Application Information

#### 8.2.2.1 Pull-up Resistor Selection

Since the TLV4011 has an open drain output, care should be taken in selecting the pull-up resistor ( $R_{PU}$ ) value to ensure proper output voltage levels. First, consider the required output high logic level requirement of the logic device that is being driven by the comparator when calculating the maximum  $R_{PU}$  value. When in a logic high output state, the output impedance of the comparator is very high but there is a finite amount of leakage current that needs to be accounted for. Use  $I_{OH}$  from the EC Table and the  $V_{IH}$  minimum from the logic device being driven to determine  $R_{PU}$  maximum using [Equation 4](#).

$$R_{PU}(\max) = \frac{(V_{PU} - V_{IH(\min)})}{I_{OH}} \quad (4)$$

Next, determine the minimum value for  $R_{PU}$  by using the  $V_{IL}$  maximum from the logic device being driven. In order for the comparator output to be recognized as a logic low,  $V_{IL}$  maximum is used to determine the upper boundary of the comparator's  $V_{OL}$ .  $V_{OL}$  maximum for the comparator is available in the EC Table for specific sink current levels and can also be found from the  $V_{OUT}$  versus  $I_{SINK}$  curve in the Typical Application curves. A good design practice is to choose a value for  $V_{OL}$  maximum that is 1/2 the value of  $V_{IL}$  maximum for the input logic device. The corresponding sink current and  $V_{OL}$  maximum value will be needed to calculate the minimum  $R_{PU}$ . This method will ensure enough noise margin for the logic low level. With  $V_{OL}$  maximum determined and the corresponding  $I_{SINK}$  obtained, the minimum  $R_{PU}$  value is calculated with [Equation 5](#).

$$R_{PU}(\min) = \frac{(V_{PU} - V_{OL(\max)})}{I_{SINK}} \quad (5)$$

Since the range of possible  $R_{PU}$  values is large, a value between 5 k $\Omega$  and 100 k $\Omega$  is generally recommended. A smaller  $R_{PU}$  value provides faster output transition time and better noise immunity, while a larger  $R_{PU}$  value consumes less power when in a logic low output state.

#### 8.2.2.2 Input Supply Capacitor

Although an input capacitor is not required for stability, for good analog design practice, connect a 100 nF low equivalent series resistance (ESR) capacitor from (VDD) to (GND).

#### 8.2.2.3 Sense Capacitor

Although not required in most cases, for extremely noisy applications, place a 1 nF to 100 nF bypass capacitor from the comparator input (SENSE) to the (GND) for good analog design practice. This capacitor placement reduces device sensitivity to transients.

## 9 Power Supply Recommendations

The TLV4011 comparator is designed to operate from an input supply from 1.3 V to 6 V. It is recommended to place a 0.1- $\mu$ F capacitor from the VDD pin to GND.

## 10 Layout

### 10.1 Layout Guidelines

TI recommends to place the 0.1- $\mu$ F decoupling capacitor close to the VDD pin. The VDD trace should be able to carry 6  $\mu$ A without a significant drop in voltage. Avoid a long trace from the SENSE pin to the resistor divider.

### 10.2 Layout Examples

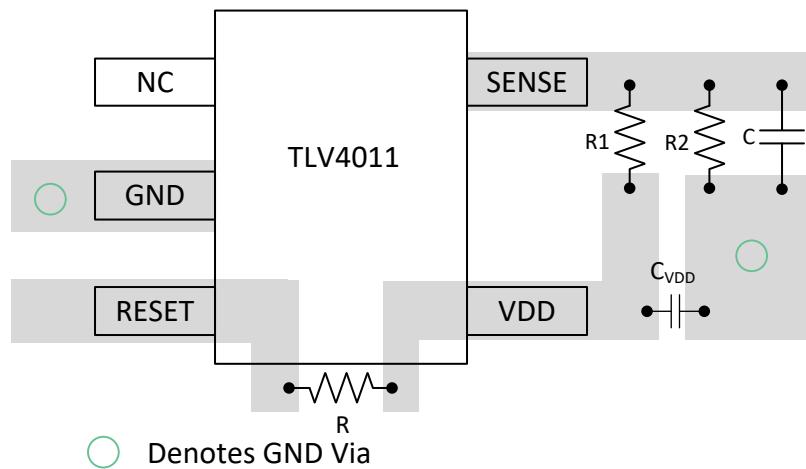


Figure 13. Layout Example

## 11 Device and Documentation Support

### 11.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](http://ti.com). In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 11.2 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

### 11.3 Trademarks

E2E is a trademark of Texas Instruments.

### 11.4 Electrostatic Discharge Caution

 This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

 ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 11.5 Glossary

#### [SLYZ022 — TI Glossary](#).

This glossary lists and explains terms, acronyms, and definitions.

## 12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TLV4011DCKR	Active	Production	SC70 (DCK)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	1HK
TLV4011DCKR.B	Active	Production	SC70 (DCK)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	1HK

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF TLV4011 :**

- Automotive : [TLV4011-Q1](#)

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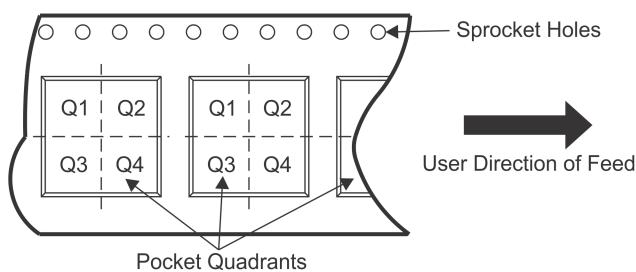
NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLV4011DCKR	SC70	DCK	5	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3

**TAPE AND REEL BOX DIMENSIONS**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLV4011DCKR	SC70	DCK	5	3000	180.0	180.0	18.0

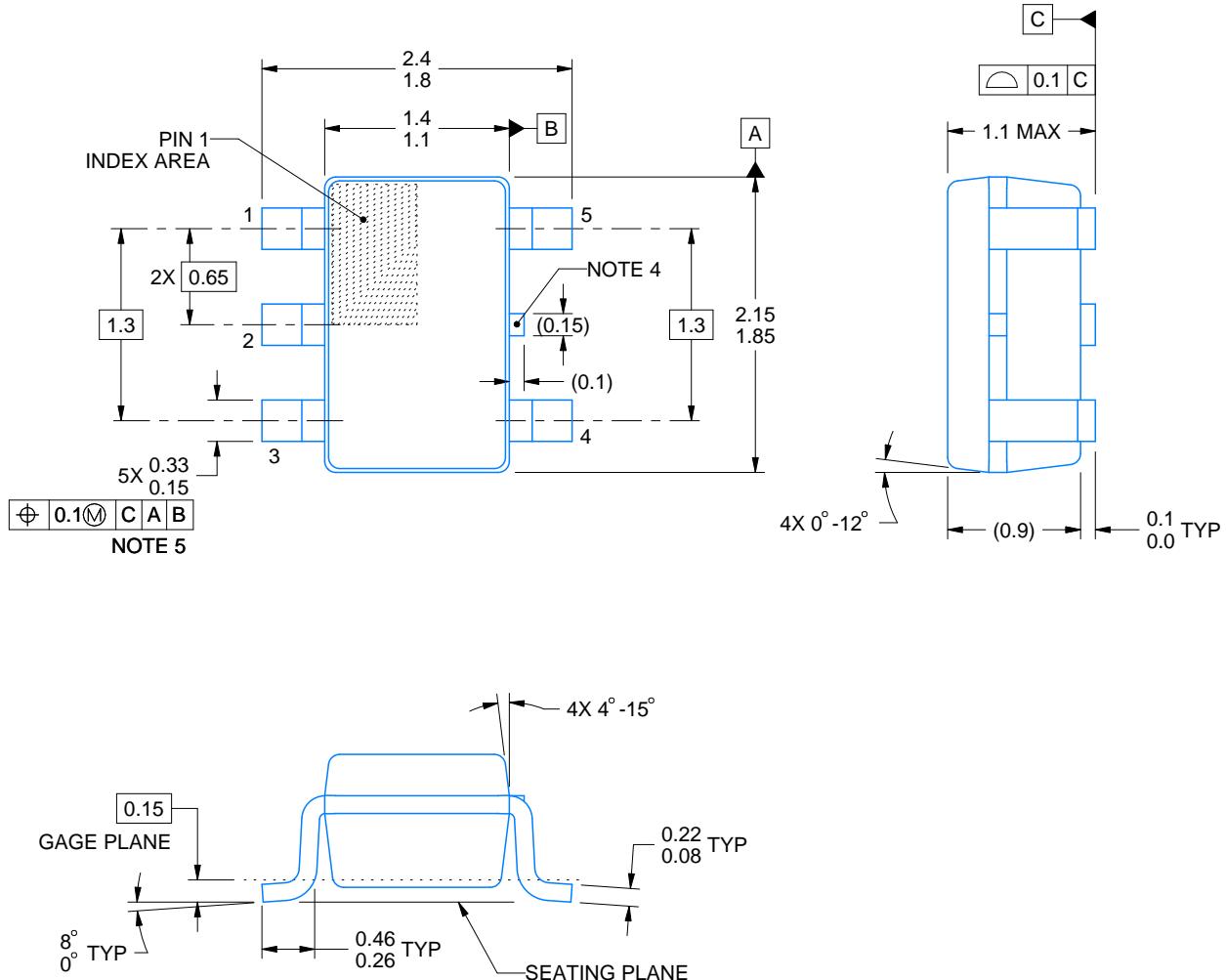
## PACKAGE OUTLINE

**DCK0005A**



## SOT - 1.1 max height

## SMALL OUTLINE TRANSISTOR



## NOTES:

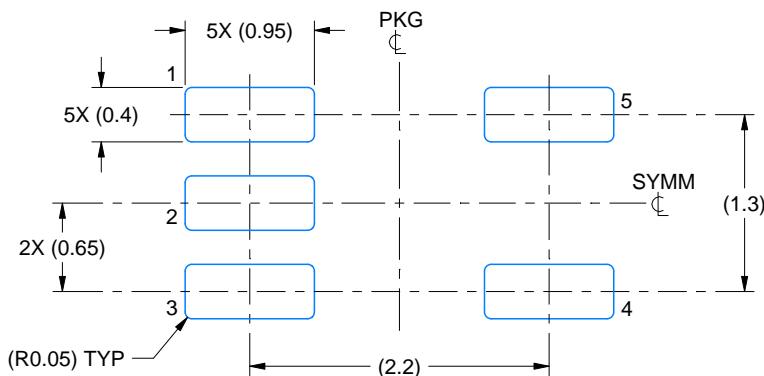
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-203.
4. Support pin may differ or may not be present.
5. Lead width does not comply with JEDEC.
6. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25mm per side

# EXAMPLE BOARD LAYOUT

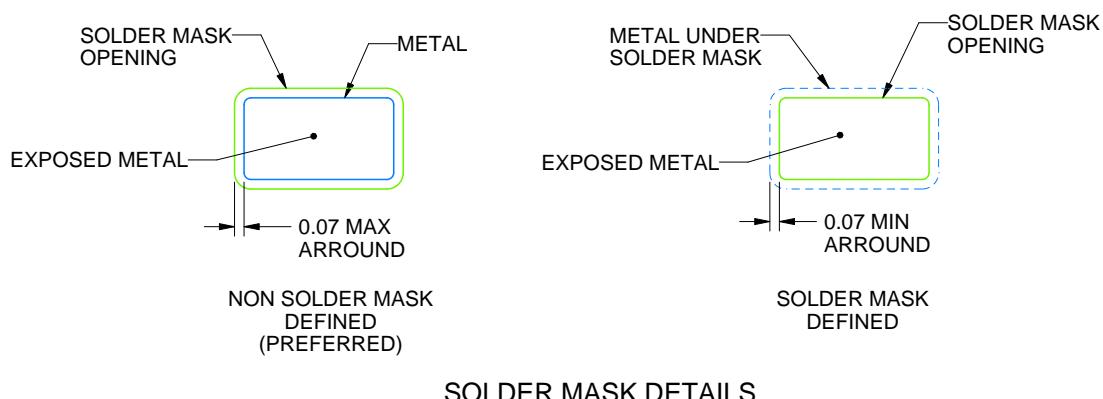
DCK0005A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:18X



SOLDER MASK DETAILS

4214834/G 11/2024

NOTES: (continued)

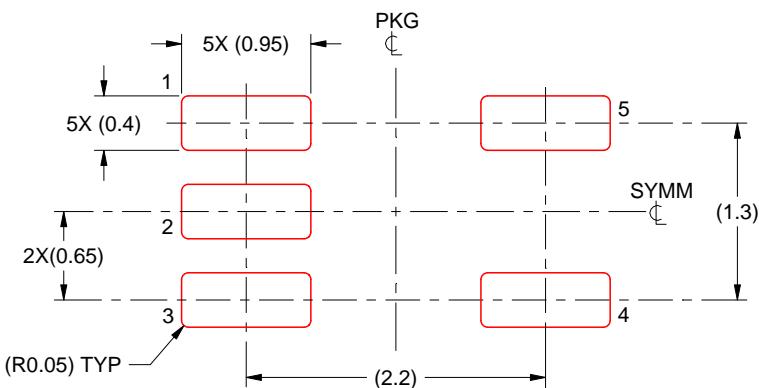
7. Publication IPC-7351 may have alternate designs.
8. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DCK0005A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE  
BASED ON 0.125 THICK STENCIL  
SCALE:18X

4214834/G 11/2024

NOTES: (continued)

9. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
10. Board assembly site may have different recommendations for stencil design.

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